

PRODUCTION QUALITY WAFER PROCESSING EQUIPMENT

LEARN MORE!



Temporary Bonding Equipment

PRODUCT OFFERINGS

The Cee® suite of wafer processing equipment is a complete system for developing production quality processes in R&D, laboratory, or low-volume production environments.



BOND

The Apogee® Bonder allows for precise temporary bonding for various wafer sizes and types, yielding impressive results without the inconvenience, size, and cost of a track system.



SLIDE DEBOND

With the Cee® 1300CSX Thermal Slide Debonder, you can enjoy process flexibility that accommodates your evolving needs, whether you are in a low-volume environment or production-fab ready.



MECHANICAL DEBOND

The Apogee® Mechanical Debonder offers gentle, room-temperature "peel" separation minimizing stress on the wafer pair. As a bonus, it is compatible with a range of materials and thermal budget requirements.

CONTACT US TODAY



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